



Ion beam analysis of Tritiated thin films

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**With thanks to W.R. Wampler, B.L. Doyle, G. Bond,
B. Vaandrager, K. Arstila, and P. Pusa.**

Motivation: metal tritide films

- ◆ Metal tritide films are essential for applications such as neutron generators.
 - **Problems:**
 - T decays to ^3He , forming bubbles and stressing the film.
 - O contamination influences hydriding efficiency and film stability.
- ◆ Tritide film composition and other properties are needed for understanding and controlling hydriding and aging problems.
- ◆ Several types of films are being studied:
 - ErT_2 films with 100% T, studied as the films age
 - ErD_2 films hydrided under various conditions
- ◆ Here we present:
 - Three examples of high energy, heavy ion ERD profiling of ^3He , T, D, H, O and C in these types of samples.

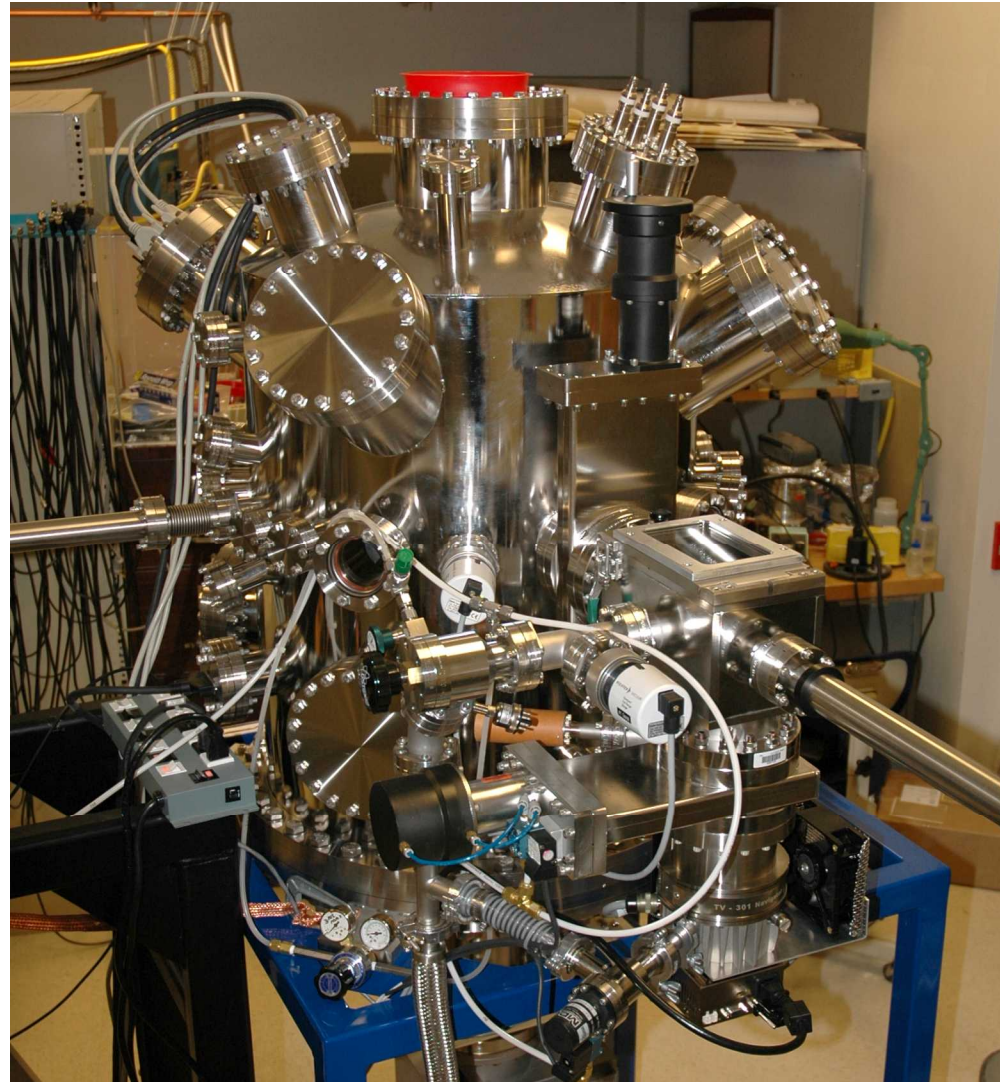
High energy ERD system

◆ Problem:

- Need to analyze T, ^3He , D, H, O, and C.
- Our existing ERD analysis chamber used for T could not measure ^3He or O on Si.
- New system designed based on high energy, heavy ion beams and ΔE -E detectors.

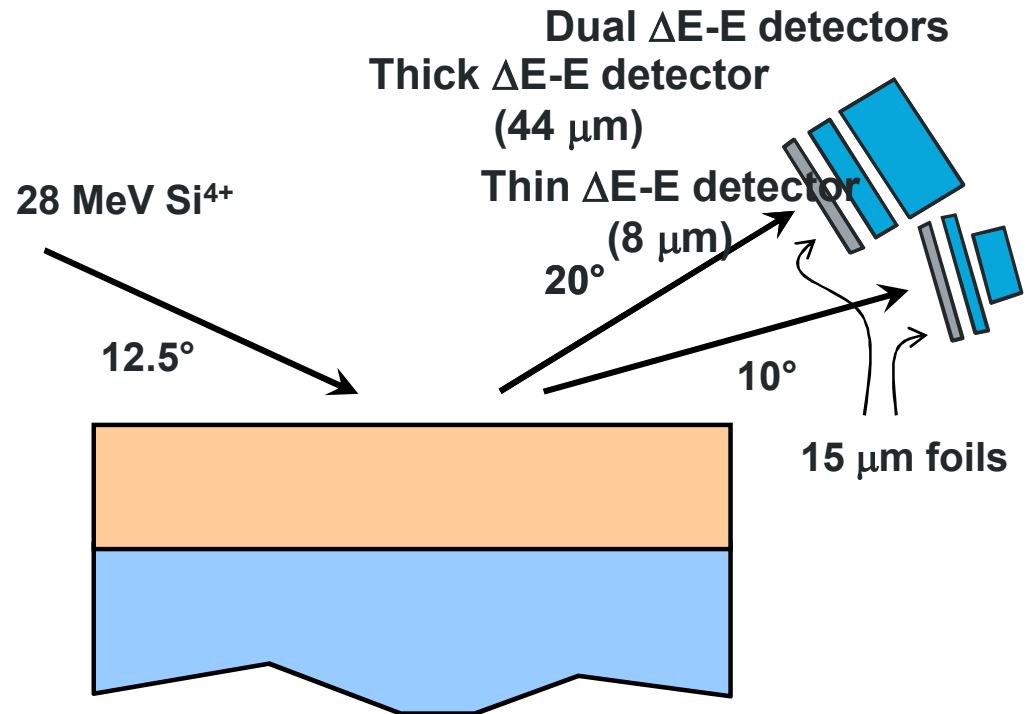
◆ Analysis chamber:

- beam line on 7 MV Tandem
- 6-axis custom goniometer
- all-metal ion-pumped chamber
- load lock with heating stage



Analysis method

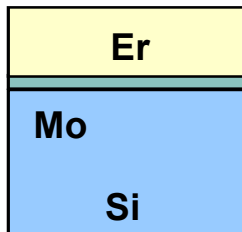
- Heavy ion elastic recoil detection (ERD) with 28 MeV Si^{4+} analysis beam incident at 12.5°
- Thick ΔE -E detector to profile H, D, T, ^3He
- Thin ΔE -E detector to profile O, C
- Each detector pair has a $15\ \mu\text{m}$ foil to block the Si analysis beam and curved slits to optimize resolution.



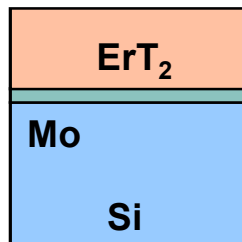
Example: ErT_2 layers on Mo/Si

Sample preparation

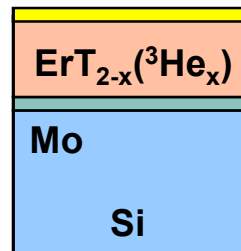
500 nm Er
95 nm Mo
Silicon



Hydrided
with 100%
T at LANL



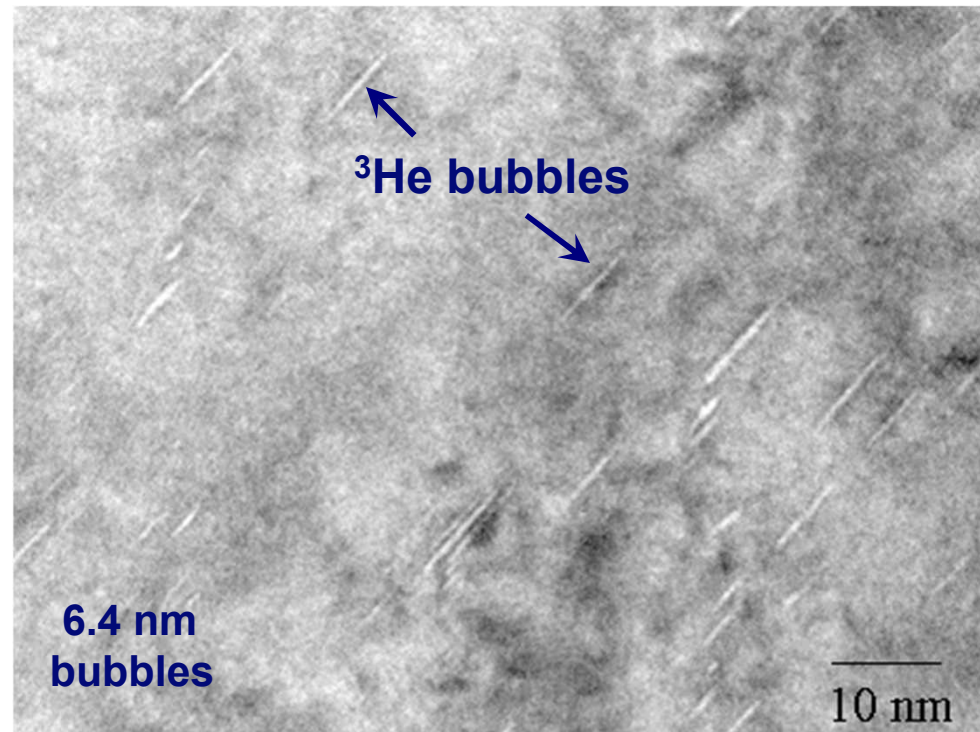
Aged in
vacuum



Oxide forms during hydriding and upon air exposure.

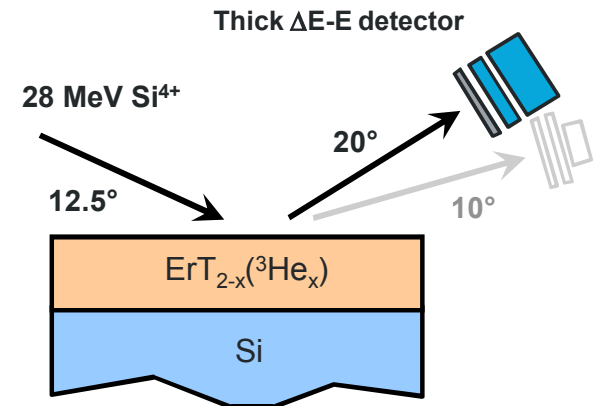
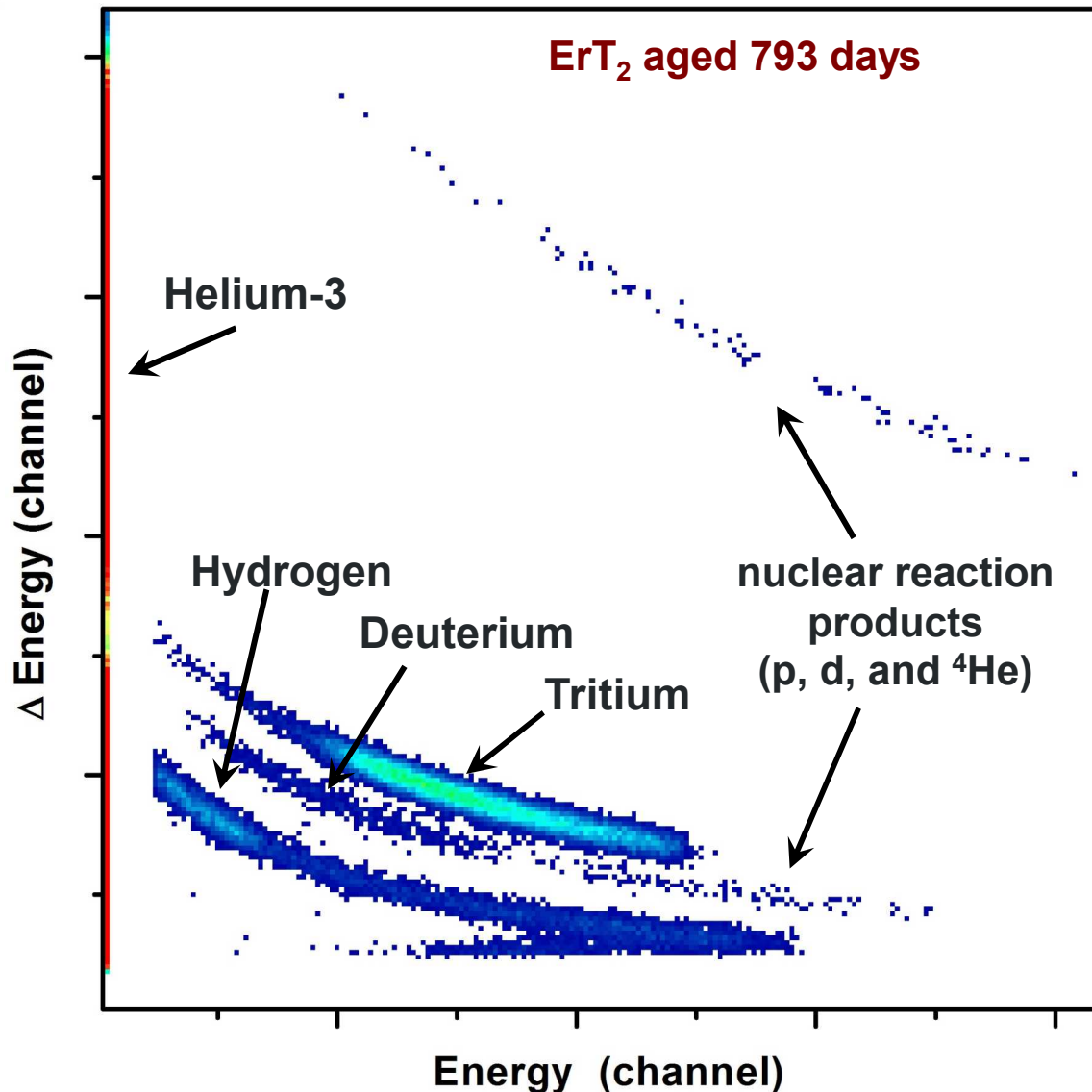
Tritium decays into ^3He , forming platelet-like bubbles on (111) planes.

TEM cross-section
bright-field, $\sim\{110\}$ zone
62 days after hydriding.



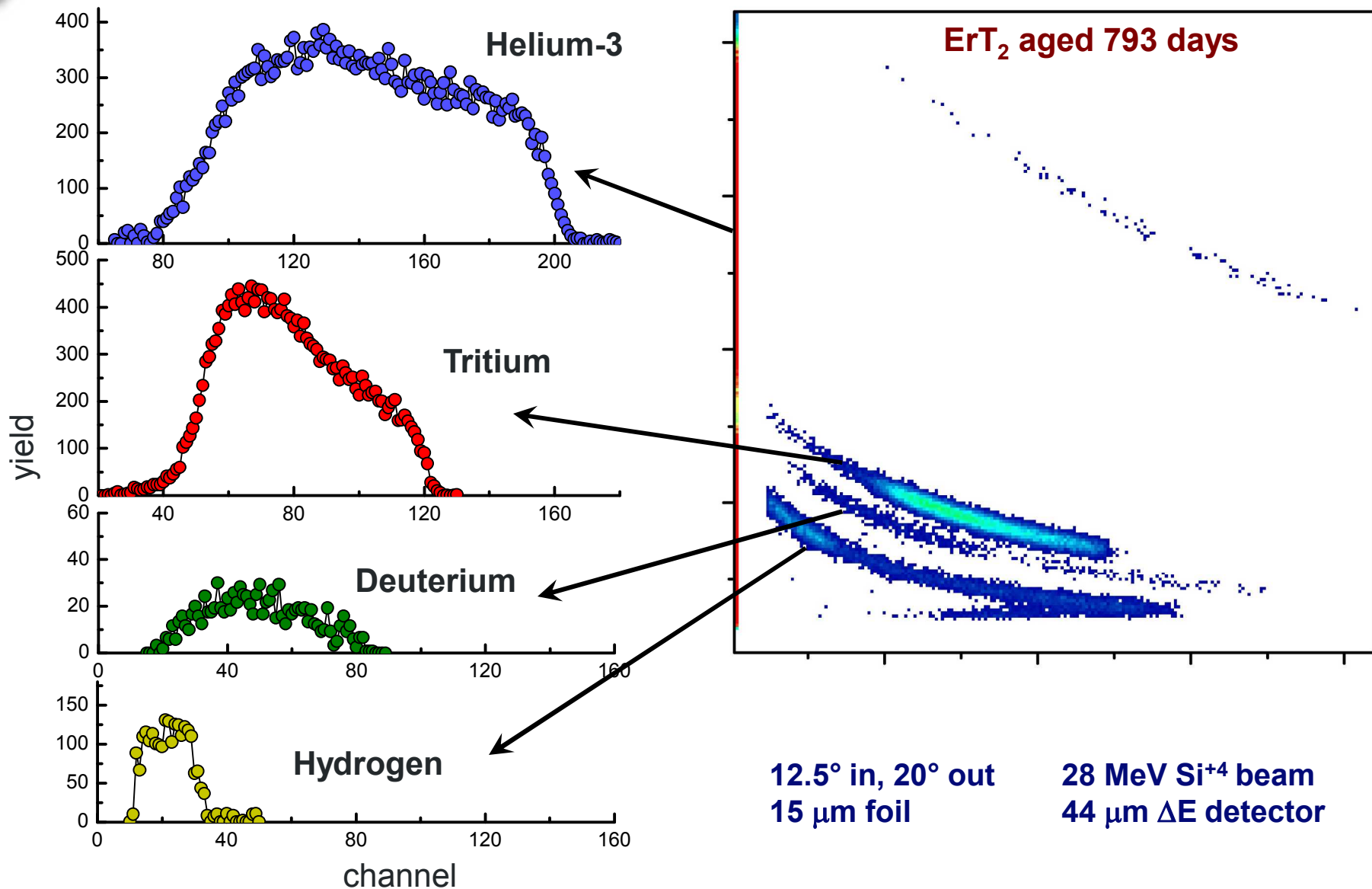
TEM with Gillian Bond, New Mexico Institute of Mining and Technology

Coincidence map for **thick** ΔE -E detector

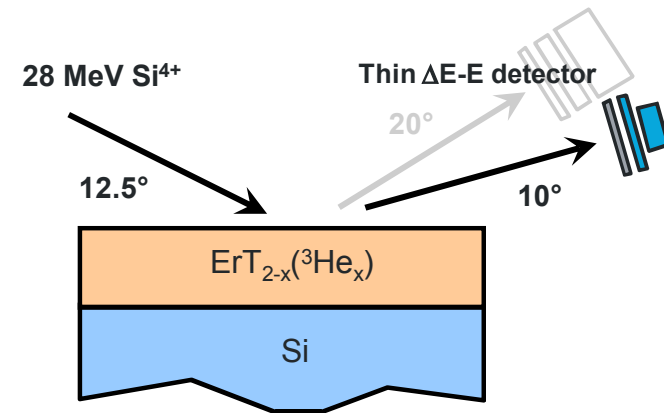
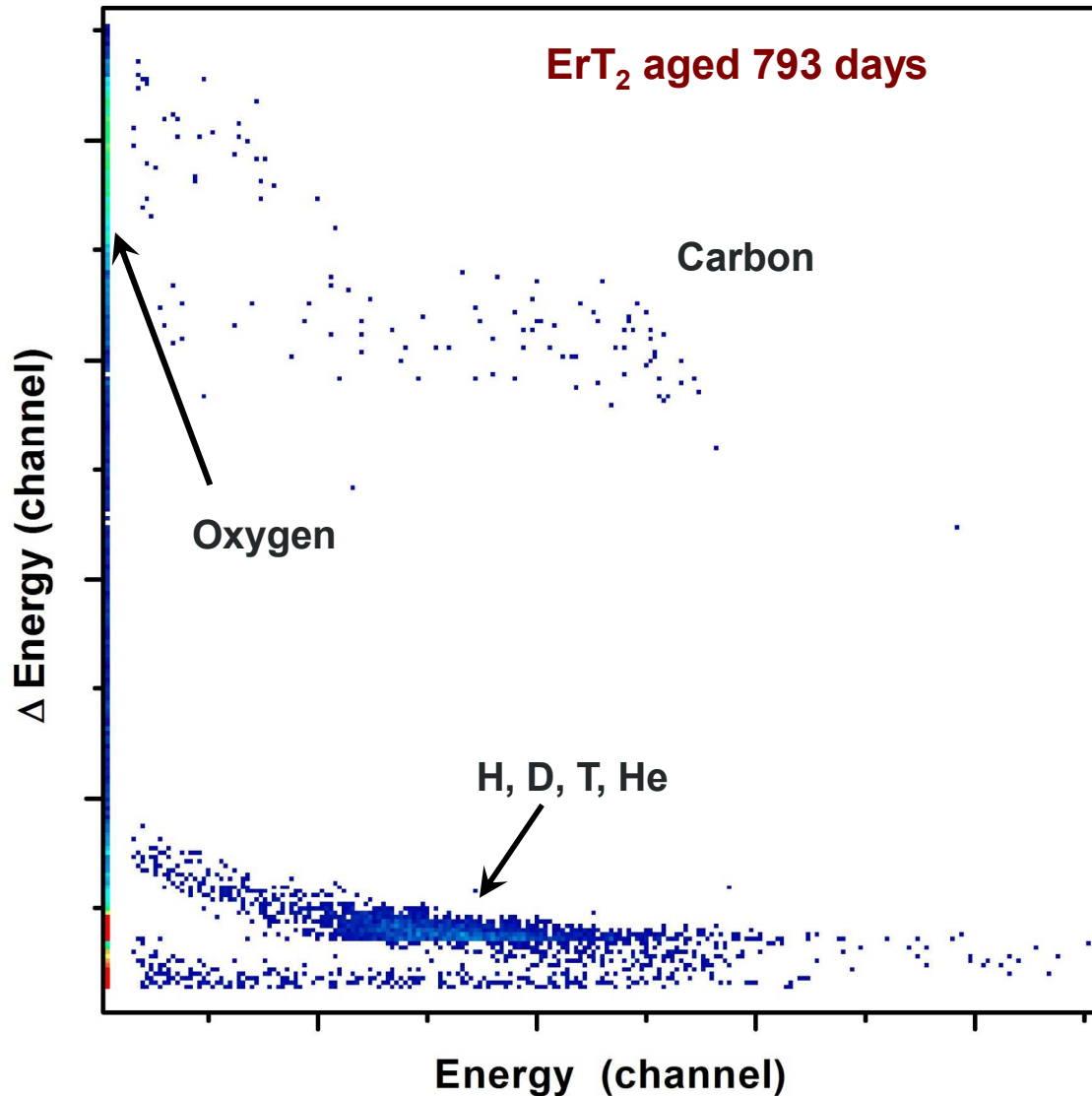


12.5° in, 20° out
28 MeV Si⁴⁺ beam
15 μ m foil
44 μ m ΔE detector

Spectra for **thick** ΔE -E detector

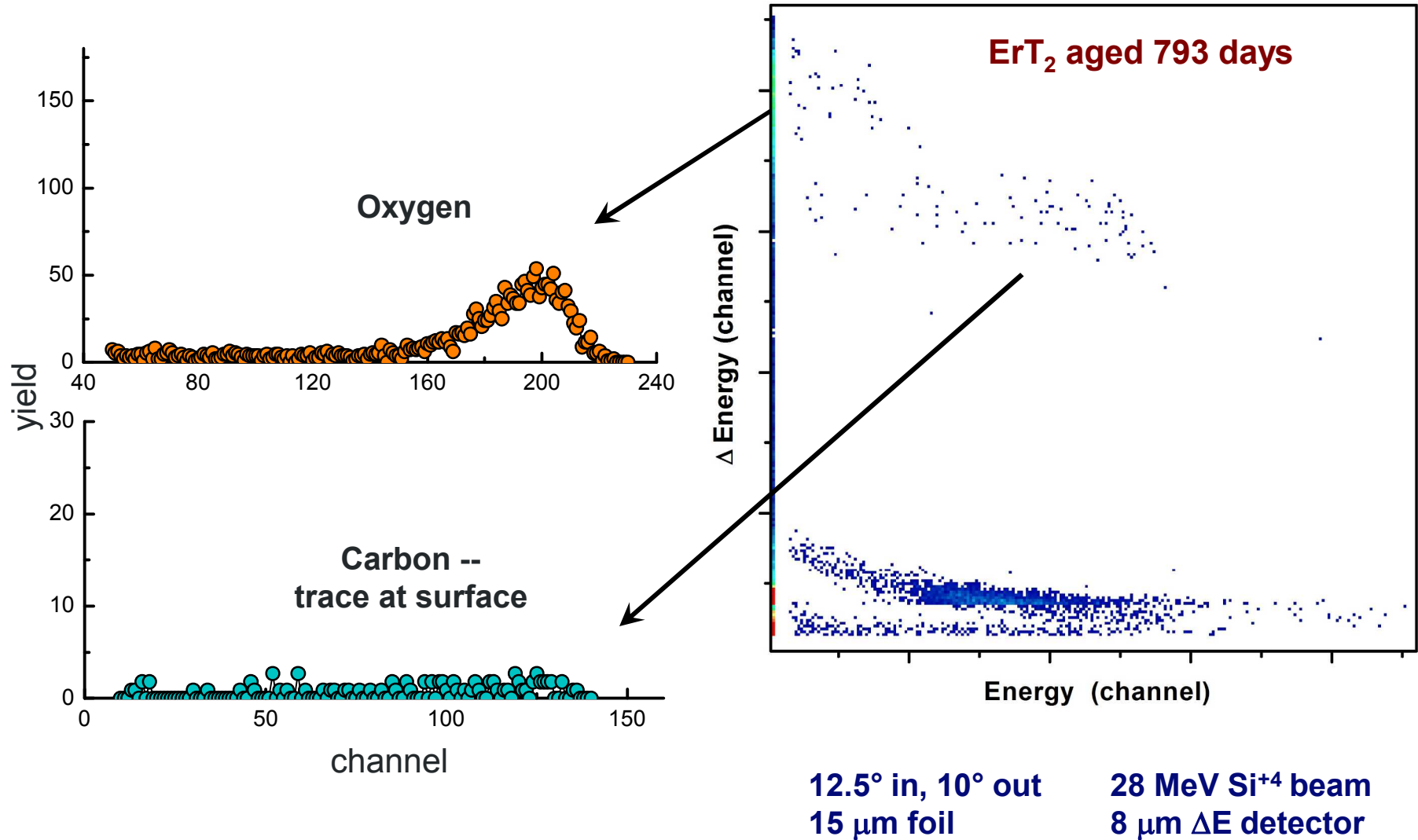


Coincidence map for **thin** ΔE -E detector



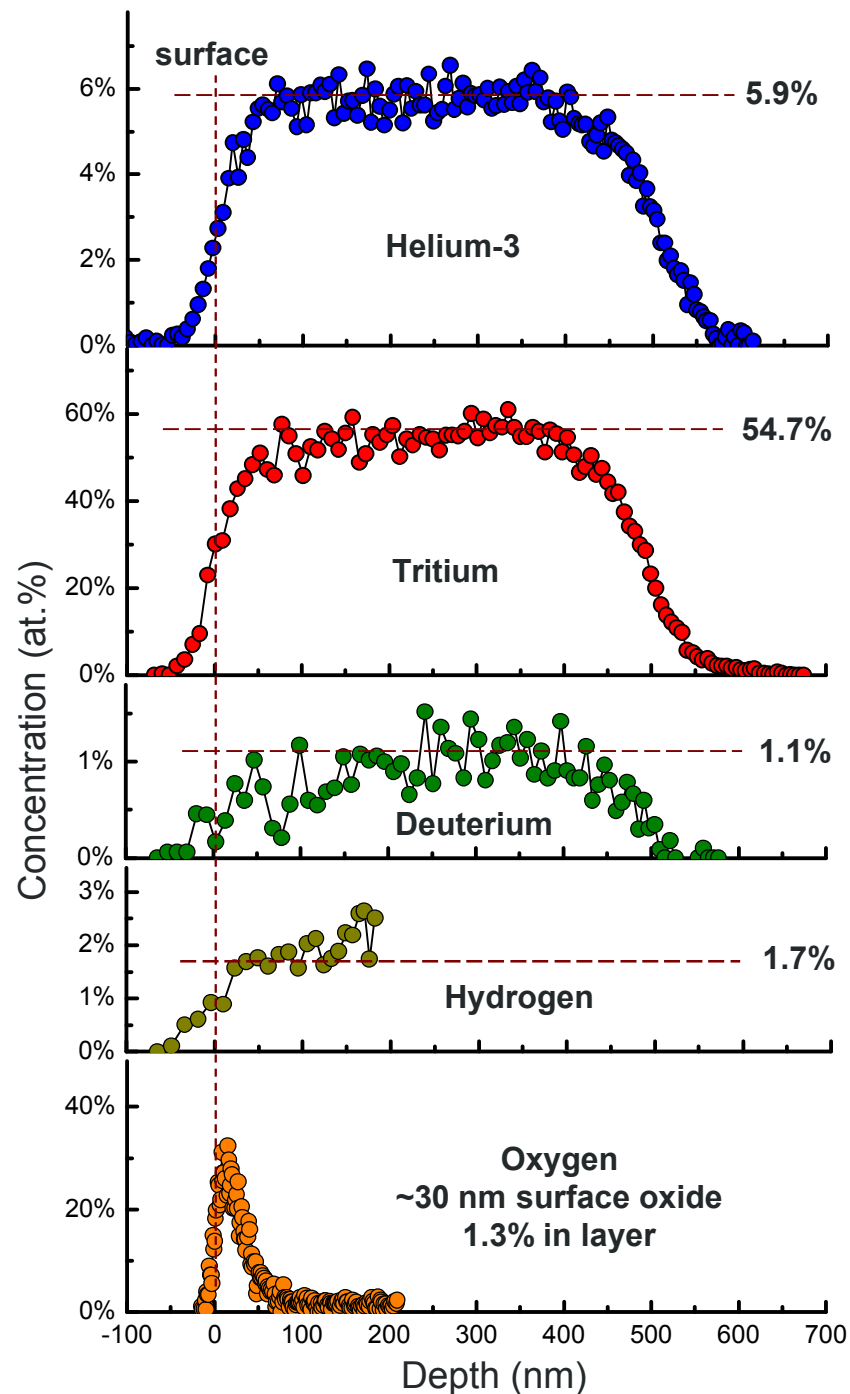
12.5° in, 10° out
28 MeV Si⁴⁺ beam
15 μ m foil
8 μ m ΔE detector

Spectra for **thin** ΔE -E detector



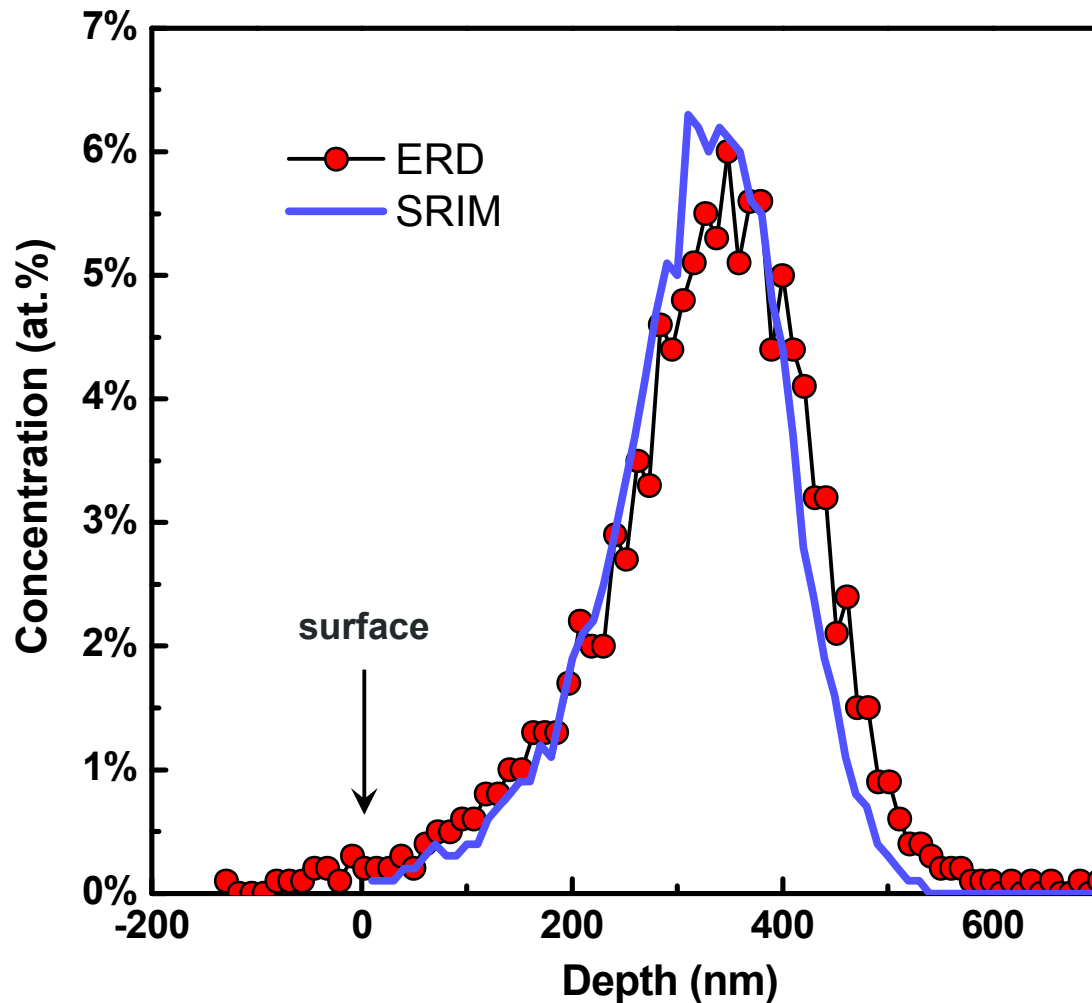
Profiles using SIMNRA

- Spectral data scaled in depth and atomic concentration using SIMNRA simulations.
- Broadening due to straggling and roughness has not been removed.
- Depth scales calculated using the density of ErH_2 .
- Indicated concentrations are in the bulk of the layer. Near surface concentrations are lower due to Oxygen.
- T cross-section is non-Rutherford and was deduced by fitting T spectra obtained at 24–30 MeV, calibrated with lower energy He ERD. ^3He cross-section may also need calibration.



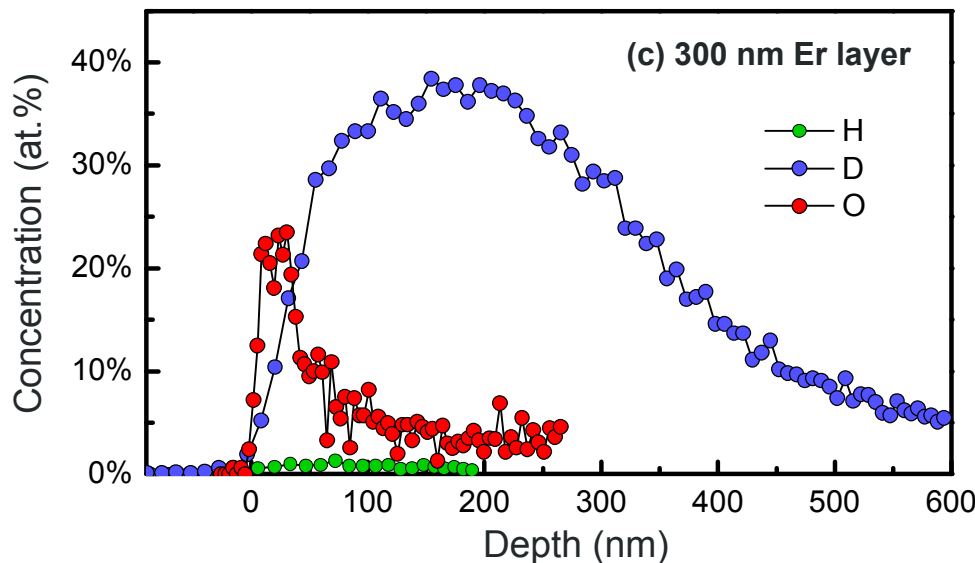
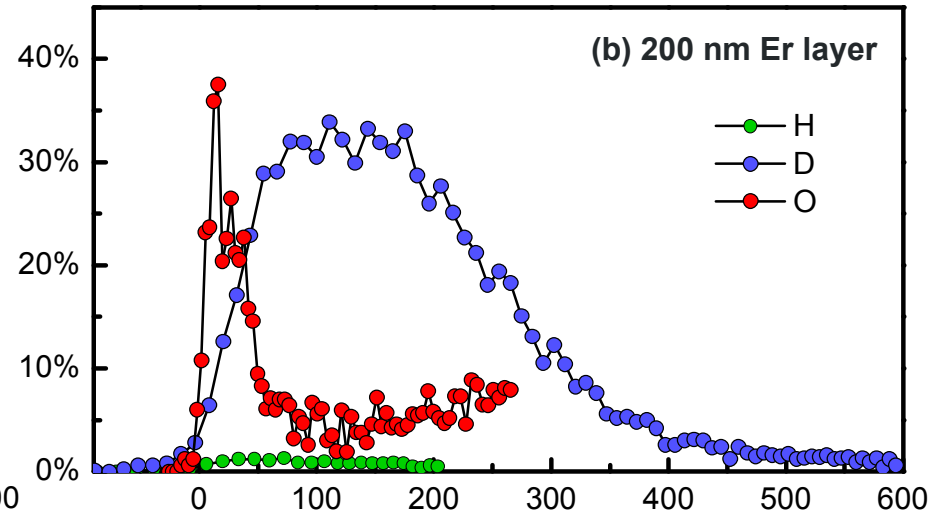
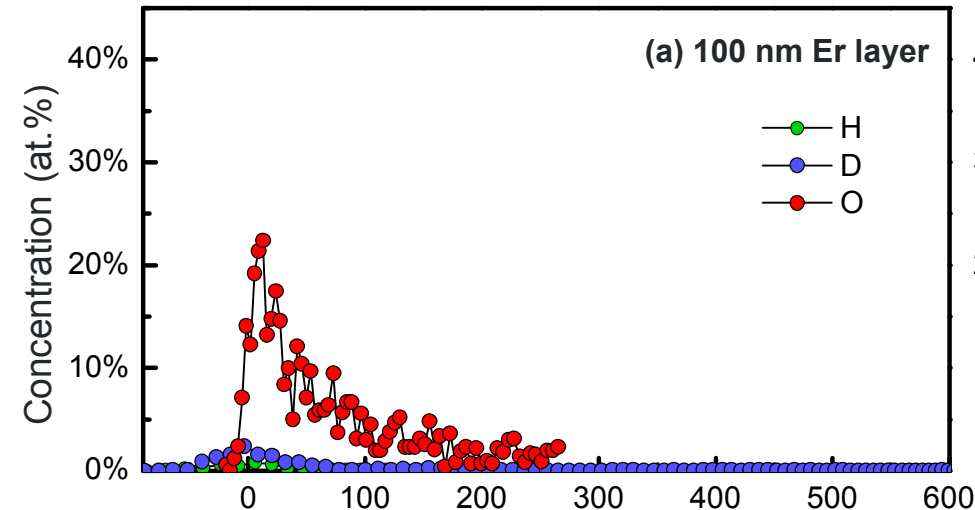
Example: ^3He -implanted Si

$1.6 \times 10^{16} \text{ } ^3\text{He}/\text{cm}^2$ implanted at 40 keV into Si.



- Spectral data scaled in depth and atomic concentration using SIMNRA simulations.
- Broadening due to straggling and roughness has not been removed.
- Depth scale calculated using the density of Si.
- SRIM 2003 was used to estimate the implant profile.

Example: Deuteriding Er layers



- Er layers 100, 200, and 300 nm were loaded with Deuterium at 150°C.
- Oxidation prevents the thinnest layer from hydriding and interferes with the other two.
- SIMNRA and the density of ErH_2 were used to calculate the profiles.

Samples from L.I. Espada, C.R. Tewell and S.H. King.



Summary

Model ErT_2 films have been fabricated and are being examined with a variety of techniques as they age.

Other hydride films are being examined to deduce the effect of contamination on the hydriding process.

The new ERD system allows non-destructive profiling of ^3He , T, H, D, O, and C with down to 10 nm resolution, limited by surface roughness.